

## Electronic Patent Application Fee Transmittal

Application Number:	10801867			
Filing Date:	17-Mar-2004			
Title of Invention:	Assembly of semiconductor device, interposer and substrate			
First Named Inventor/Applicant Name:	Jun Otsuka			
Filer:	Abraham Jacob Rosner/Michelle Delozier			
Attorney Docket Number:	Q79598			
Filed as Large Entity				
<b>Utility Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	790	790
<b>Total in USD (\$)</b>				<b>790</b>